

SGL50N60RUF

Short Circuit Rated IGBT

General Description

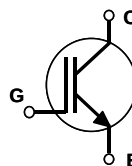
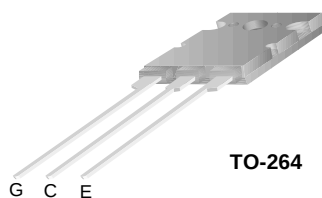
Fairchild's RUF series of Insulated Gate Bipolar Transistors (IGBTs) provide low conduction and switching losses as well as short circuit ruggedness. The RUF series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

Features

- Short circuit rated 10us @ $T_C = 100^\circ\text{C}$, $V_{GE} = 15\text{V}$
- High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.2\text{V}$ @ $I_C = 50\text{A}$
- High input impedance

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Description	SGL50N60RUF	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	80	A
	Collector Current @ $T_C = 100^\circ\text{C}$	50	A
$I_{CM(1)}$	Pulsed Collector Current	150	A
T_{SC}	Short Circuit Withstand Time @ $T_C = 100^\circ\text{C}$	10	us
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	250	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	100	W
T_J	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	0.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	25	$^\circ\text{C/W}$

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	600	--	--	V
ΔB _V _{CES} /ΔT _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA	--	0.6	--	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0V	--	--	250	uA
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0V	--	--	± 100	nA
On Characteristics						
V _{GE(th)}	G-E Threshold Voltage	I _C = 50mA, V _{CE} = V _{GE}	5.0	6.0	8.5	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 50A, V _{GE} = 15V	--	2.2	2.8	V
		I _C = 80A, V _{GE} = 15V	--	2.5	--	V
Dynamic Characteristics						
C _{ies}	Input Capacitance	V _{CE} =30V, V _{GE} = 0V, f = 1MHz	--	3311	--	pF
C _{oes}	Output Capacitance		--	399	--	pF
C _{res}	Reverse Transfer Capacitance		--	139	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{CC} = 300 V, I _C = 50A, R _G = 5.9Ω, V _{GE} = 15V, Inductive Load, T _C = 25°C	--	26	--	ns
t _r	Rise Time		--	89	--	ns
t _{d(off)}	Turn-Off Delay Time		--	66	100	ns
t _f	Fall Time		--	118	200	ns
E _{on}	Turn-On Switching Loss		--	1.68	--	mJ
E _{off}	Turn-Off Switching Loss		--	1.03	--	mJ
E _{ts}	Total Switching Loss	V _{CC} = 300 V, I _C = 50A, R _G = 5.9Ω, V _{GE} = 15V, Inductive Load, T _C = 125°C	--	2.71	3.8	mJ
t _{d(on)}	Turn-On Delay Time		--	28	--	ns
t _r	Rise Time		--	91	--	ns
t _{d(off)}	Turn-Off Delay Time		--	68	110	ns
t _f	Fall Time		--	261	400	ns
E _{on}	Turn-On Switching Loss		--	1.7	--	mJ
E _{off}	Turn-Off Switching Loss		--	2.31	--	mJ
E _{ts}	Total Switching Loss		--	4.01	5.62	mJ
T _{sc}	Short Circuit Withstand Time		V _{CC} = 300 V, V _{GE} = 15V, @ T _C = 100°C	10	--	--
Q _g	Total Gate Charge	V _{CE} = 300 V, I _C = 50A, V _{GE} = 15V	--	145	210	nC
Q _{ge}	Gate-Emitter Charge		--	25	35	nC
Q _{gc}	Gate-Collector Charge		--	70	100	nC
L _e	Internal Emitter Inductance	Measured 5mm from PKG	--	18	--	nH

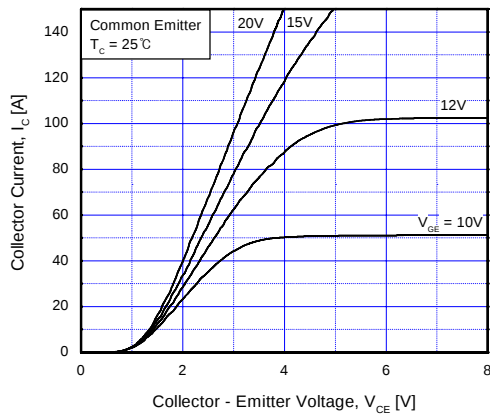


Fig 1. Typical Output Characteristics

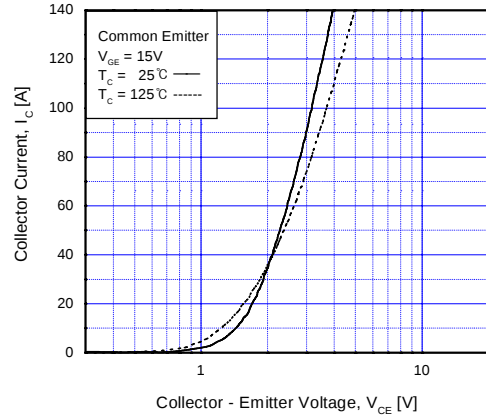


Fig 2. Typical Saturation Voltage Characteristics

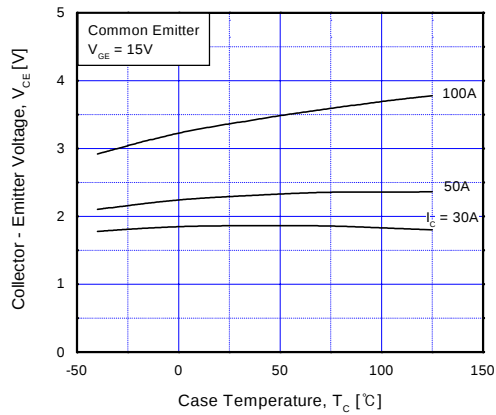


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

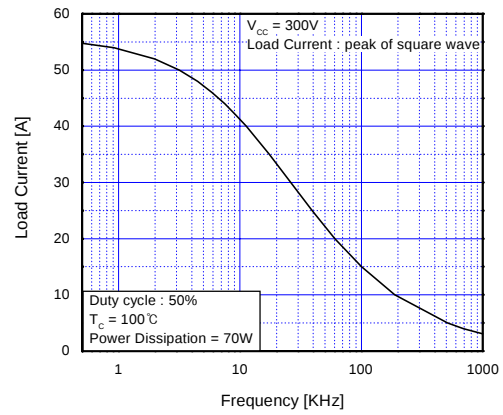


Fig 4. Load Current vs. Frequency

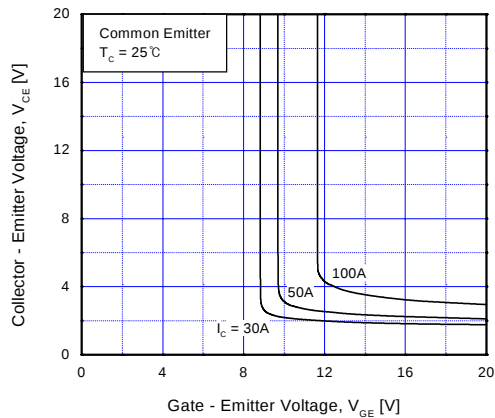


Fig 5. Saturation Voltage vs. V_{GE}

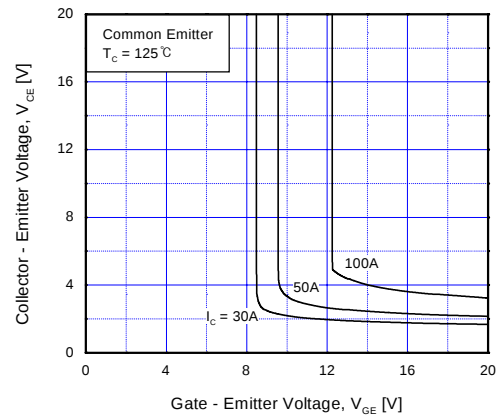


Fig 6. Saturation Voltage vs. V_{GE}

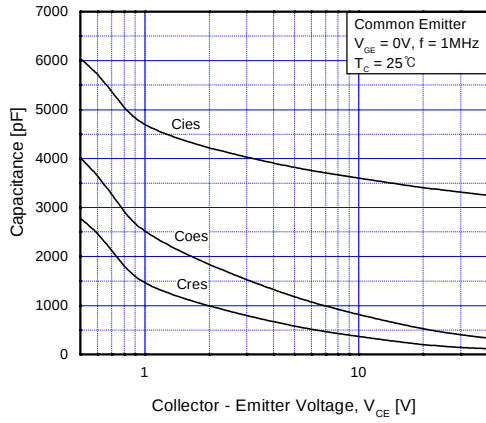


Fig 7. Capacitance Characteristics

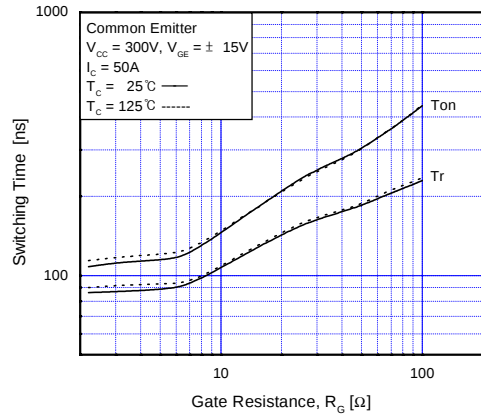


Fig 8. Turn-On Characteristics vs. Gate Resistance

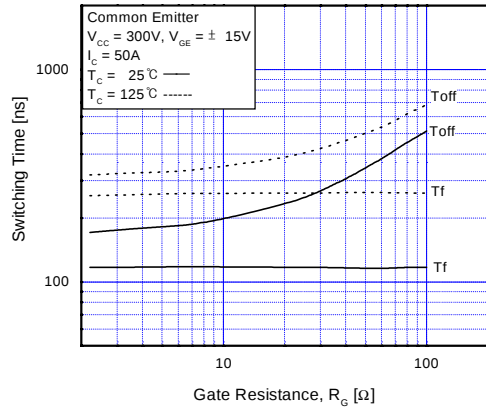


Fig 9. Turn-Off Characteristics vs. Gate Resistance

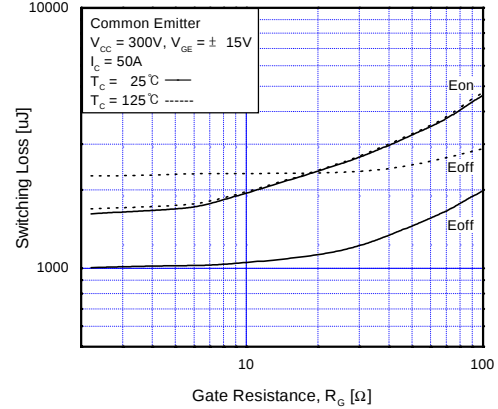


Fig 10. Switching Loss vs. Gate Resistance

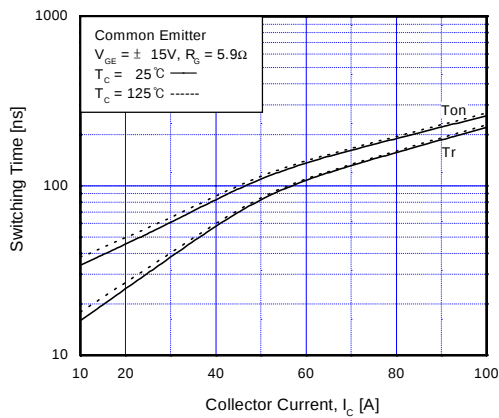


Fig 11. Turn-On Characteristics vs. Collector Current

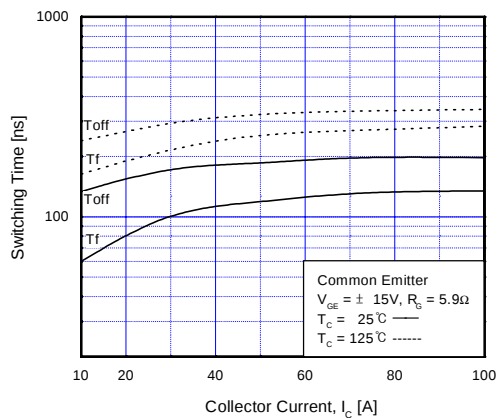


Fig 12. Turn-Off Characteristics vs. Collector Current

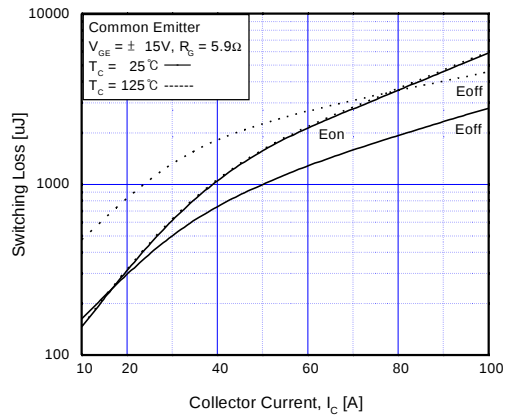


Fig 13. Switching Loss vs. Collector Current

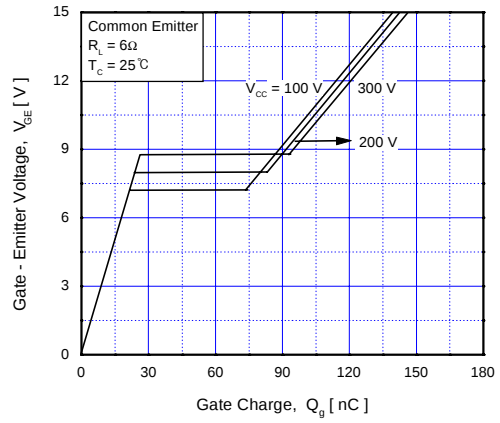


Fig 14. Gate Charge Characteristics

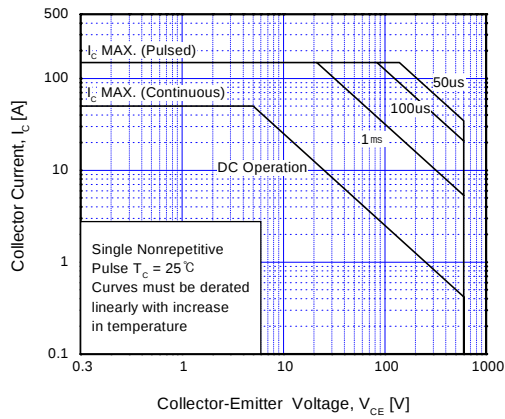


Fig 15. SOA Characteristics

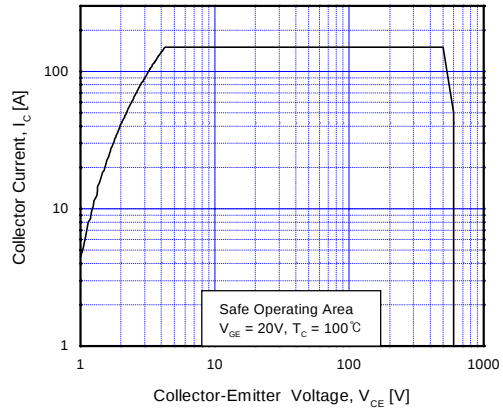


Fig 16. Turn-Off SOA Characteristics

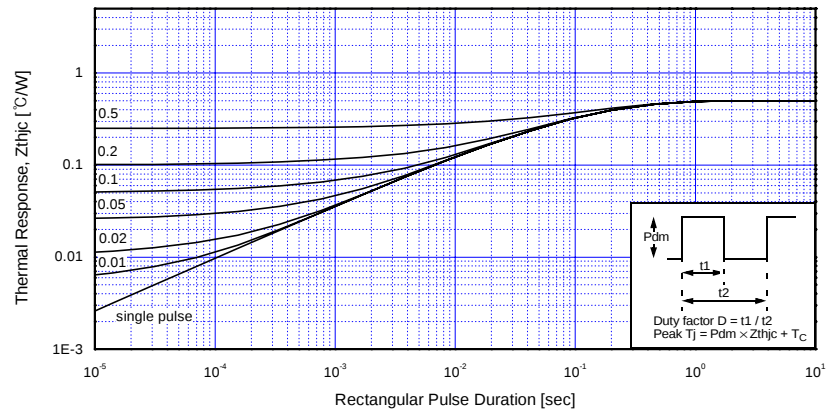


Fig 17. Transient Thermal Impedance of IGBT

SGL50N60RUF

Technical drawing of a mechanical part, likely a bracket or base plate, showing top and side views with dimensions in millimeters.

Top View Dimensions:

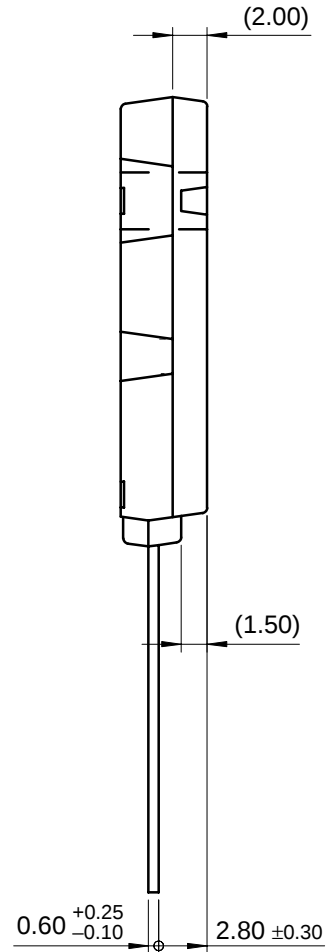
- Overall width: 20.00 ± 0.20
- Overall height: 20.00 ± 0.20
- Central hole diameter: $\phi 3.30 \pm 0.20$
- Corner hole radii: $(R1.00)$ and $(R2.00)$
- Distance from center to corner hole center: (8.30)
- Distance from center to side hole center: (7.00)
- Distance from center to bottom hole center: (7.00)
- Distance from center to top hole center: (9.00)
- Distance from center to bottom hole center: (11.00)
- Distance from center to top hole center: (9.00)
- Distance from center to side hole center: (1.00)
- Distance from center to bottom hole center: (0.50)
- Distance from center to top hole center: (2.00)
- Distance from center to bottom hole center: (2.00)
- Distance from center to top hole center: (4.00)
- Distance from center to bottom hole center: (6.00 ± 0.20)

Side View Dimensions:

- Overall height: 20.00 ± 0.50
- Overall width: 20.00 ± 0.20
- Central slot width: 1.50 ± 0.20
- Distance from center to side hole center: (1.50)
- Distance from center to bottom hole center: (1.50)
- Distance from center to top hole center: (1.50)
- Distance from center to bottom hole center: (3.00 ± 0.20)
- Distance from center to top hole center: (3.00 ± 0.20)
- Distance from center to bottom hole center: $(1.00^{+0.25}_{-0.10})$
- Distance from center to top hole center: $(1.00^{+0.25}_{-0.10})$
- Distance from center to bottom hole center: (2.50 ± 0.10)
- Distance from center to top hole center: (2.50 ± 0.10)
- Distance from center to bottom hole center: (5.45 ± 0.30)
- Distance from center to top hole center: (5.45 ± 0.30)

Material and Tolerances:

- Material: 5.45TYP
- Tolerance: $[5.45 \pm 0.30]$



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